AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph starting at page 6, line 8 and ending at page 7, line 2 as follows:

The phase transition material used in the present invention absorbs or releases heat as latent heat in an amount of 10 J/g or more, preferably 30 J/g or more at lower temperature than fusion temperature of the matrix resin material. The phase transition material absorbs or releases heat as latent heat in an amount of 10 J/g or more at a lower fusion-crystallization temperature than fusion temperature of the matrix resin material. For examples, it is selected from the group consisting of zeolite powder, polytriphenylphosphate, crystalline paraffin wax, polyethyleneglycol, fatty acid, naphthalene, calcium bichloride, polyepsilon caprolactone, polyethylene oxide, polyisobutylene, ~~polycyclopenten~~ polycyclopentene, polycyclooctene, ~~polycyclododecne~~ polycyclododecene, polyisoprene, polyoxytriethylene, polyoxytetramethylene, polyoxyoctamethylene, polyoxypropylene, polybutyrolactone, polyvalerolactone, polyethyleneadipate, polyethylene suberate, polydecamethylazelate, and a mixture thereof. Even if these organic and inorganic materials are selected, if fusion-crystallization temperature is higher than fusion temperature of the matrix resin, they cannot absorb and release heat at applied temperature.

Please amend the paragraph at page 8, lines 1-15 as follows:

And, the composition of the present invention may further comprise one or more kinds of thermally conductive additives. The thermally conductive additive can be a ceramic or metal having thermal conductivity of 5 W/m-K or more. For examples, the thermally conductive additive is selected from the group consisting of copper, silver, gold, steel, nickel, silicon carbide, boron nitride, diamond, beryllium oxide, boron phosphide, aluminum nitride, beryllium sulfide, boron azenide, silicon, gallium nitride, aluminum phosphide, gallium ~~phophide~~ phosphide, and a mixture thereof. The thermally conductive additive is preferably contained in the composition in an amount of 5 to 90 parts by weight, based on 100 parts by weight of the total amount of the matrix resin and the phase transition material. If the content is less than 5 parts by weight, thermal conductivity increasing effect is insufficient, and if the content is more than 90 parts by weight, heat absorb-release is insufficient.

Please amend the Table starting at page 13, line 1 as follows:

[Table 1] (unit: wt%)

	Example 1	Example 2
Matrix	Polypropylene 35	Polybutyleneterephthalate 35
Phase change material	Paraffin wax 15	Stearic acid 15
Compatibilizer	Ethylene vinylacetate 12	Maleic anhydride- ethylene copolymer 10
Thermally conductive additive	Silicon carbide 38	~~Silicn~~ Silicon carbide 40
Reinforcing additive	-	-
Heat-absorb/release amount	16 J/g at about 55°C	14 J/g at about 30°C
Heat deflection temperature	80°C	85°C
Impact strength	3 kg.cm/cm	3 kg.cm/cm
Flexural Modulus	17000 kg/cm2	23000 kg/cm2
Thermal conductivity (room temperature)	0.6 W/m-K	1.0 W/m-K

Please amend the paragraph starting at page 20, line 22 and ending at page 21, line 3 as follows:

An injection molded sample was prepared by the same method as in Example 1, except that a resin composition comprising 60

wt% of ~~polyutylene~~ polybutylene terephthalate and 40 wt% of silicon carbide was used. Heat deflection temperature, impact strength, Flexural Modulus, heat absorb-release amount, and thermal conductivity were measured by the same method as in Example 1.